ISMP 2015

14th International Symposium on Microelectronics and Packaging

October 13(Tue) - 15(Thu), 2015
KINTEX Hall2, Seoul / Ilsan, Korea

http://ismp2015.kmeps.or.kr

Organized by: The Korean Microelectronics and Packaging Society
Supported by: Korea Semiconductor Industry Association
It is our pleasure to announce that the 14th International Symposium on Microelectronics and Packaging (ISMP 2015) will be held at KINTEX (Korea International Exhibition Center) convention center located at Seoul/IlSan Korea during October 13-15 2015. This international conference is organized by KMEPS (the Korean Microelectronics and Packaging Society), and will address comprehensive coverage of recent advances in Materials, Processing, Simulation, Printed Electronics, Nano/Micro Joining Technology and Reliability of Electronic Packaging. The technical sessions for oral and poster presentations will be in parallel with the 17th International Semiconductor Exhibition (http://www.sedex.org) at KINTEX. The ISMP 2015 will provide an excellent opportunity for scientists and engineers of academic institutes and industries to discuss recent advances in electronic packaging technology and forecast new technological directions. We cordially invite you to submit abstracts for the conference, and look forward to welcoming you in Seoul, Korea.

General Chairman of ISMP 2015,  Ho Jung Chang, Ph.D

### SYMPOSIUM TOPICS

ISMP 2015 will include all fundamental and applied sciences and technologies related to the fields of electronic materials, devices, and packagings. Topics may include from, but are not limited to, the following areas:

- Electronic Materials and Processing
- Optoelectronic and Photonic Materials and Processing
- Advanced Packaging Technologies
- 3D Integration and Packaging
- LED Packaging and Applications
- MEMS Packaging and Applications
- Modeling, Simulation, Quality and Reliability of Electronic Components
- Nanomaterials and its Application Technology
- Micro/Nano Joining Technology
- Interconnection Materials and its Reliability
- IoT (Internet of Things), Sensor Devices and System
- Soldering and Surface Mount Technology
- Wearable and Stretchable Electronics
- Printed Electronics and Materials
You are invited to submit a 300-word abstract through the email (kmeps@kmeps.or.kr) including title, authors, affiliations, address and corresponding author (refer to abstract template) by May 31, 2015 for oral and poster presentations. Acknowledgement of your abstract submission will be sent to the presenting/corresponding authors' email addresses by July 15, 2015.

**PAPER PUBLICATION**

Authors whose abstracts are accepted will be requested to submit full manuscript by August 15, 2015 (Manuscript submission is not mandatory). After peer review, all accepted papers will be published in following several leading SCI(E) and KCI journals.

- Soldering and Surface Mount Technology (SCIE)
- Materials Transactions (SCI)
- Journal of Nanoelectronics and Optoelectronics (SCIE)
- Nanoscience and Nanotechnology Letters (SCIE)
- Journal of Microelectronics and Packaging Society (KCI)
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October 13(Tue)-15(Thu), 2015  KINTEX Hall2, Seoul / Ilsan, Korea

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**IMPORTANT DATES**

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<tr>
<td>Submission of Abstract</td>
<td>May 31, 2015</td>
</tr>
<tr>
<td>Notification of Acceptance</td>
<td>July 15, 2015</td>
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<tr>
<td>Pre-registration</td>
<td>August 15, 2015</td>
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<tr>
<td>Submission of Final Manuscript</td>
<td>August 15, 2015</td>
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<tr>
<td>Conference</td>
<td>October 13-15, 2015</td>
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**REGISTRATION**

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<tr>
<th>Category</th>
<th>Pre-Registration</th>
<th>On-site Registration</th>
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<tbody>
<tr>
<td></td>
<td>Overseas</td>
<td>Domestic</td>
</tr>
<tr>
<td>Regular</td>
<td>USD 450</td>
<td>KRW 450,000</td>
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<tr>
<td>Student</td>
<td>USD 200</td>
<td>KRW 200,000</td>
</tr>
<tr>
<td>Banquet</td>
<td>USD 100 / KRW 100,000</td>
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</tbody>
</table>

**** Registration fee includes symposium program book with USB abstract proceeding, welcome party and luncheon coupons and free entrance ticket for the Korea Electronic Exhibition Show.

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**WELCOME PARTY**

DATE: OCTOBER 13, 6 PM
VENUE: KINTEX

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**BANQUET**

DATE: OCTOBER 14, 6 PM
VENUE: STANFORD HOTEL ([http://www.stanfordseoul.com/seoul](http://www.stanfordseoul.com/seoul))

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**ACCOMMODATIONS**

- **STANFORD HOTEL**
  - Tel: +82-2-6016-0001
  - [http://www.stanfordseoul.com](http://www.stanfordseoul.com)

- **MVL HOTEL KINTEX**
  - Tel: +82-031-927-7700
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  - [http://www.hotelpresident.co.kr](http://www.hotelpresident.co.kr)

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  - Tel: +82-2-6272-1101
  - [https://ibis.ambatel.com](https://ibis.ambatel.com)

- **MARIGOLD HOTEL**
  - Tel: +82-2-326-5588
  - [http://www.hotelmarigold.co.kr](http://www.hotelmarigold.co.kr)

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**CONTACT**

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[http://www.kmepts.or.kr](http://www.kmepts.or.kr)

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**CONFERENCE LANGUAGE**

The official language of the conference is English

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Please submit the abstract through the email [kmeps@kmepts.or.kr](mailto:kmeps@kmepts.or.kr) and you can find your submission of you abstract at [http://ismp2015.kmepts.or.kr](http://ismp2015.kmepts.or.kr)
The Korea International Exhibition Center (KINTEX) is a brand new convention center located within 45 minutes from Seoul’s downtown and showcases heavy industry products. As the largest exhibition center in Korea, KINTEX offers 5 exhibition halls and 23 meeting rooms in the space of 53,975㎡. Since its opening in April 2005, KINTEX has undergone the first of three expansion constructions, and is currently going through the second phase. When completed in September 2011, the expansion will add 53,975㎡ of exhibition space with world-class meeting facilities, placing KINTEX at the forefront of globalization and economic development in Korea.

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### i-SEDEX 2015

**International Semiconductor Exhibition**

**October 14-16, KINTEX Korea**

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<th>Section</th>
<th>Details</th>
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<tr>
<td><strong>Device</strong></td>
<td>Dram/Flash Memory, MCP, Memory module AP, MPU/MCU, DSP, DDI, PMIC, RFIC SoC etc. Foundries/Packaging Service, RFIDTag, Smart Card, Sensor, MEMS etc., Flat Panel Display (LCD, PDP, Organic EL, Etc)</td>
</tr>
<tr>
<td><strong>Factory Facility</strong></td>
<td>Air Filtering, Clean Rooms, Flow Process Control, etc.</td>
</tr>
<tr>
<td><strong>Materials</strong></td>
<td>Materials of Assembly, Chemicals &amp; Solids, Gases, FPD, Wafer Substrate</td>
</tr>
<tr>
<td><strong>Components &amp; Parts</strong></td>
<td>Process Equipment, Sub System Parts</td>
</tr>
<tr>
<td><strong>System &amp; Software</strong></td>
<td>FPGA/PLD, Wireless Communication, Interface Technology, Embedded Board Computer, CAD, Package Simulation, Test Program etc.</td>
</tr>
</tbody>
</table>

**CONTACT i-SEDEX**

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